Compliant with IEC 62474/ D9.00

MICROCHIP  Semiconductor Device Type: PKA 028 VQFN 5x6x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
		"Contained In"	% Total					I		
Basic Substance	<b>CAS Number</b>	Sub-Component	Weight	mg/part	ppm	39.05	(mg) Total	Mold Compound	% ot Total Weight	47.85
Silica, fused	60676-86-0	Mold Compound	43.065	35.141	430,650		Silica, fused	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	2.321	1.894	23,207		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.321	1.894	23,207		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.144	0.117	1,436		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	46.837	38.219	468,367			Total	100.00	•
Iron	7439-89-6	Lead Frame	0.070	0.057	704	38.30	(mg) Total	Lead Frame	% of Total Weight	46.94
Phosphorous	7723-14-0	Lead Frame	0.019	0.015	188		Copper	7440-50-8	99.78	
Zinc (Metal)	7440-66-6	Lead Frame	0.014	0.011	141		Iron	7439-89-6	0.15	
Silver (Ag)	7440-22-4	Die Attach	0.322	0.263	3,219		Phosphorous	7723-14-0	0.04	
Proprietary Resin	Trade Secret	Die Attach	0.076	0.062	759		Zinc (Metal)	7440-66-6	0.03	
Proprietary Curing agent & Hardener	Trade Secret	Die Attach	0.012	0.010	123			Total	100.00	1
Silicon	7440-21-3	Chip (Die)	2.460	2.007	24,600	0.33	(mg) Total	Die Attach	% of Total Weight	0.41
Gold	7440-57-5	Wire Bond	0.500	0.408	5.000		Silver (Aa)	7440-22-4	78.50	
Nickel	7440-02-0	Plating on external leads (pins)	1.656	1,351	16,560		Proprietary Resin	Trade Secret	18.50	
Palladium	7440-05-3	Plating on external leads (pins)	0.092	0.075	920	Prop	rietary Curing agent & Har	Trade Secret	3.00	
8 11	7440-57-5	Plating on external leads (pins)	0.092	0.075	920			Total	100.00	ı
Gold										
Gold	7440-37-3		100.000	81.600	1.000.000	2 01	Total (mg)	Chin (Die)	% of Total Weight	2 46
emiconductor device and its homogenous n	0.0816	TOTALS: g Total Mass h EU Directives: 2002/95/EC (27 January 2003) 8	100.000 & Directive 201	81.600 1/65/EU (08 Ju	1,000,000 ne 2011) and	2.01	Total (mg)  Doped Silicon	Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	2.46
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Au 14:11 : 06/28/16